

## **DIXTRA BARS 96,5Sn3Ag0,5Cu (SAC 305)**

### **FEATURES**

- Lowest Melting Point (217°C -218°C) - Excellent Fatigue Resistance - Compatible with all Flux Types - Excellent Solder Joint Reliability

### **DESCRIPTION**

SAC305 is a lead-free alloy that contains 96.5 % tin, 3% silver, and 0.5% copper. This alloy falls under the JEIDA recommendation for lead-free soldering. When used in wave soldering, DIXTRA SAC305 bar solder offers far superior fluidity as compared to other alloys and makes of bar, resulting in excellent flow. DIXTRA SAC305 bar solder also produces less dross than other bar solder, wets well, provides superior joint strength, and offers superior copper dissolution rates. DIXTRA SAC305 bar solder is alloyed in a way that results in a low drossing, high wetting solder. Dixtra process reduces suspended oxides in the solder, thus reducing drossing, improving flow and reducing bridging during soldering. SAC305 may be used with most existing equipment, processes, coatings, and flux chemistries.

### **MAX IMPURITIES LEVELS ACCORDING ISO 9453: 2014 (E)**

Al: 0,005	Au: 0,05	Cd: 0,002	Fe : 0,02	In : 0,10
As : 0,03	Bi: 0,10	Zn: 0,003	Ni: 0,01	

### **TEMPERATURE REQUIREMENTS**

Wave soldering pot temperature of 265° -270°C . Refer to the flux data sheet for specific pre-heat instructions.

### **PHYSICAL PROPERTIES**

Specific Gravity: Approx. 7.38 Melting Temperature: 217° -218°C

### **MATERIAL AVAILABILITY**

DIXTRA solder bars 96,5Sn3Ag0,5Cu (SAC305) are available in 1 Kg. Solder bar—Each box contains 25 kgs.

### **SAFETY**

Use with adequate ventilation and proper personal protective equipment.  
Refer to the accompanying MSDS for any specific emergency information.  
Do not dispose of any hazardous materials in non-approved containers.